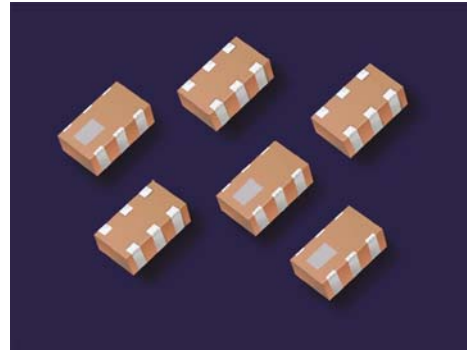


FD1608 Series

Multilayer Dual Filter



Features

- ❖ Ultra-small, low-profile and light-weight low pass filter.
- ❖ Two low pass filters are in one device.

Applications

- ❖ 0-6GHz wireless communication systems.

Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW (dB)	VSWR @ BW	Isolation In→In Out→Out (dB)	Isolation In→Out (dB)	Frequency	Attenuation (dB)
FD1608-L0918BB_	824~915	0.6 max.	1.5 max.	27 min.	30 min.	1648~1830MHz	25 min.
	1710~1910	0.6 max.		30 min.	30 min.	2472~2745MHz	25 min.
						3420~3820MHz	25 min.
						5130~5730MHz	25 min.

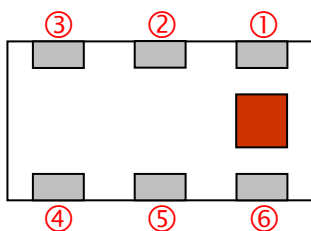
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.*
 *12 months in vacuum sealed bag and 1 week after opened. Please keep unused parts in vacuum sealed bags.
 Solder Paste : SAC 305 type is recommended.
 Power Capacity : 3W max.

Part Number

FD **1608** - **L** **0918** **BB** **□** **/LF**
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	FD :Dual Filter	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	L	④ Frequency Range	0918=900MHz /1800MHz
⑤ Specification Code	BB	⑥ Packaging	T: Tape & Reel B: Bulk

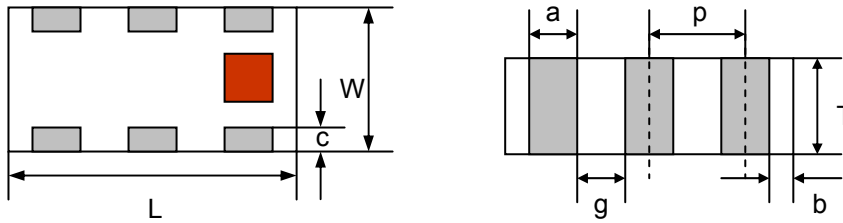
Terminal Configuration



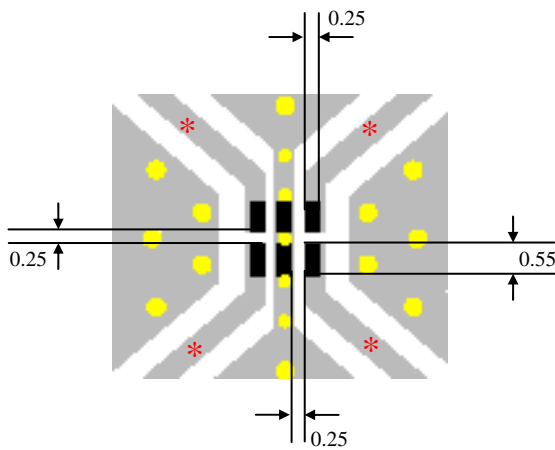
No.	Terminal Name	No.	Terminal Name
①	HB_IN	④	LB_OUT
②	GND	⑤	GND
③	LB_IN	⑥	HB_OUT

Dimensions and Recommended PC Board Pattern

Unit : mm



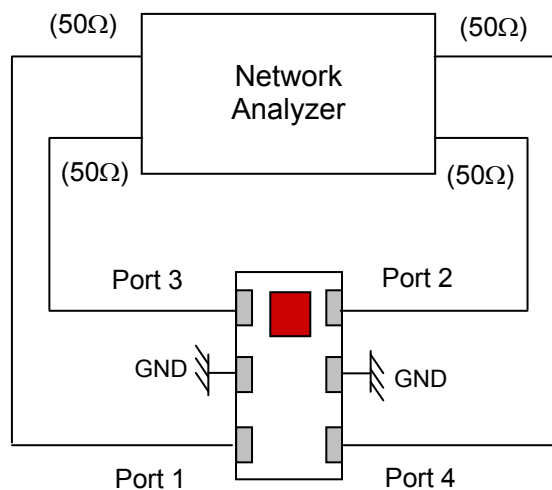
Mark	L	W	T	a	b	c	g	p
Dimensions	1.6 ± 0.1	0.8 ± 0.1	0.45max.	0.2 ± 0.1	0.2+0.1 / -0.15	0.15 ± 0.1	0.3 ± 0.1	0.50 ± 0.05



- Solder Resist
- Land
- Through-hole (ϕ 0.2 / 0.3)

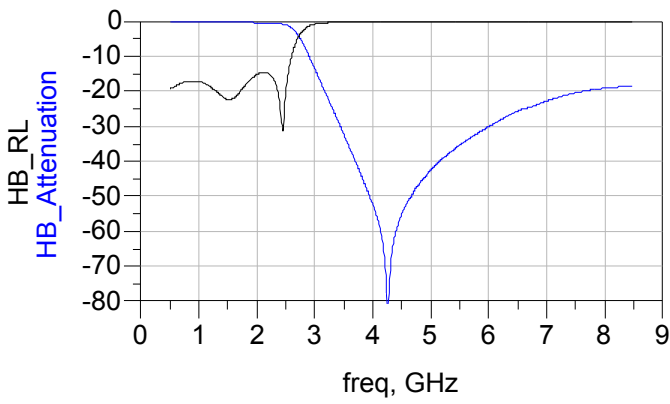
* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram

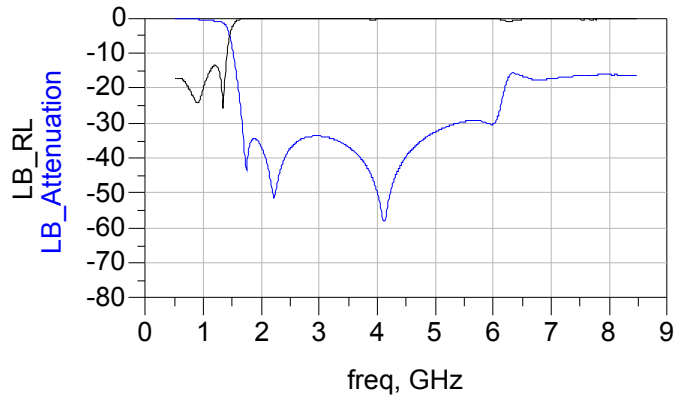


Electrical Characteristics (T=25°C)

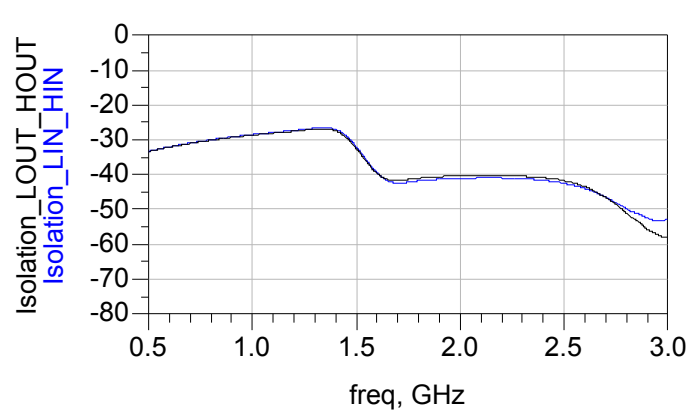
HB_In/Out (S23, S33)



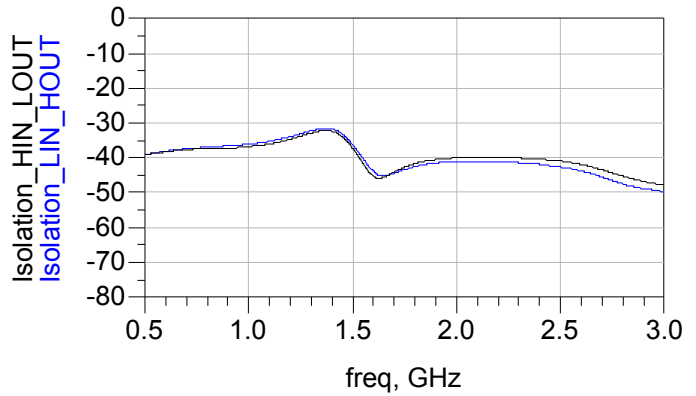
LB_In/Out (S41, S11)



Isolation_In-In/Out-Out (S31, S24)



Isolation_In-Out (S21, S43)

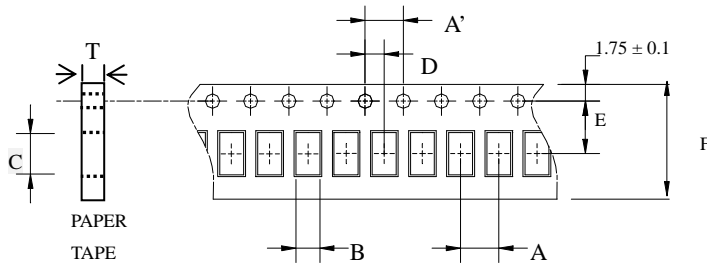


Notes

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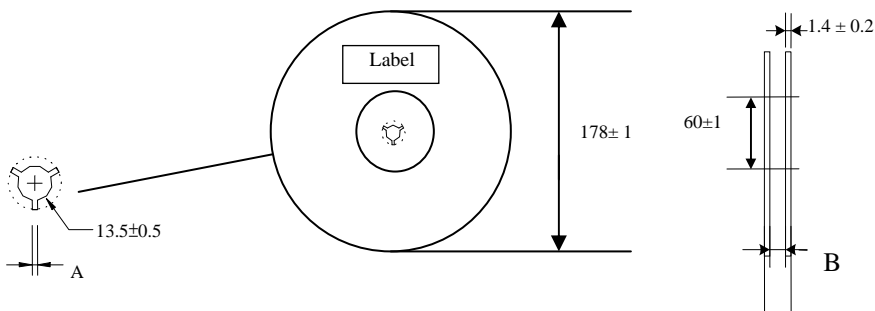
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0±	4.0±	0.95±	1.80±	2.0±	3.5±	8.0±	0.60±	4,000pcs	Paper
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.03		

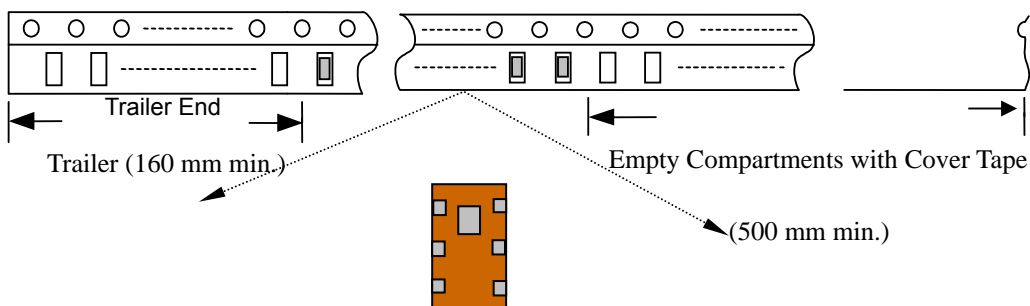
❖Reel Dimensions (Unit: mm)



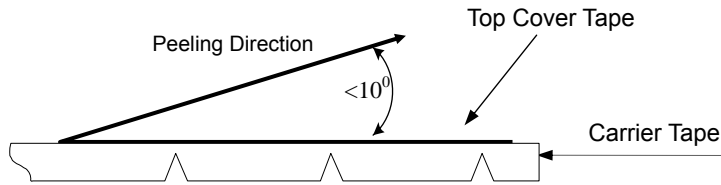
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape (Plastic material)



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

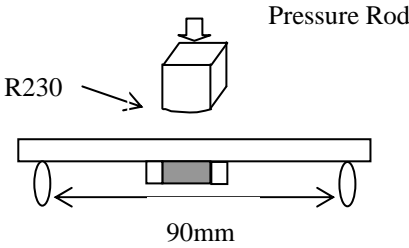
❖ **Storage Conditions**

- (1) Temperature: $15 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

Notes

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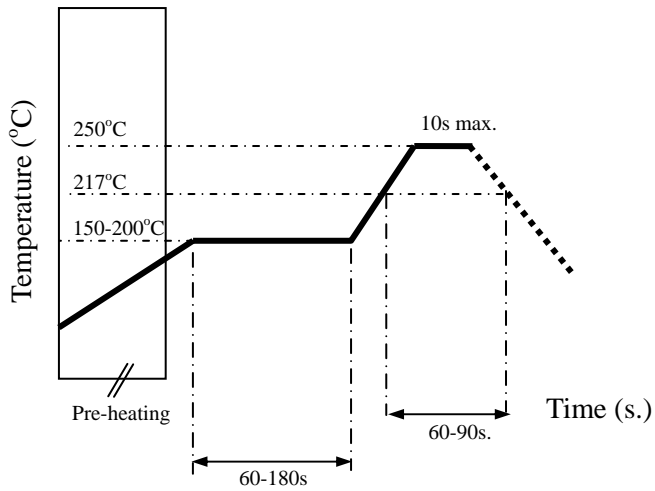
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 75% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 1kg minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



Notes

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